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(12) **United States Design Patent**
Sasaki

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(45) **Date of Patent: ** Dec. 25, 2018**

(54) **SOLID STATE RELAY**

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(**) Term: **15 Years**

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Related U.S. Application Data

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(51) **LOC (11) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/159**

(58) **Field of Classification Search**
USPC D13/103, 110, 112, 118, 133, 146, 147, D13/154, 158, 159–161, 173, 174, 178, D13/182, 184, 199
CPC G02B 27/00; H01H 47/00; H01L 23/36; H01L 23/49; H01L 25/16; H01R 4/02; H01R 4/30; H01R 9/24; H01R 9/242; H03K 17/687
See application file for complete search history.

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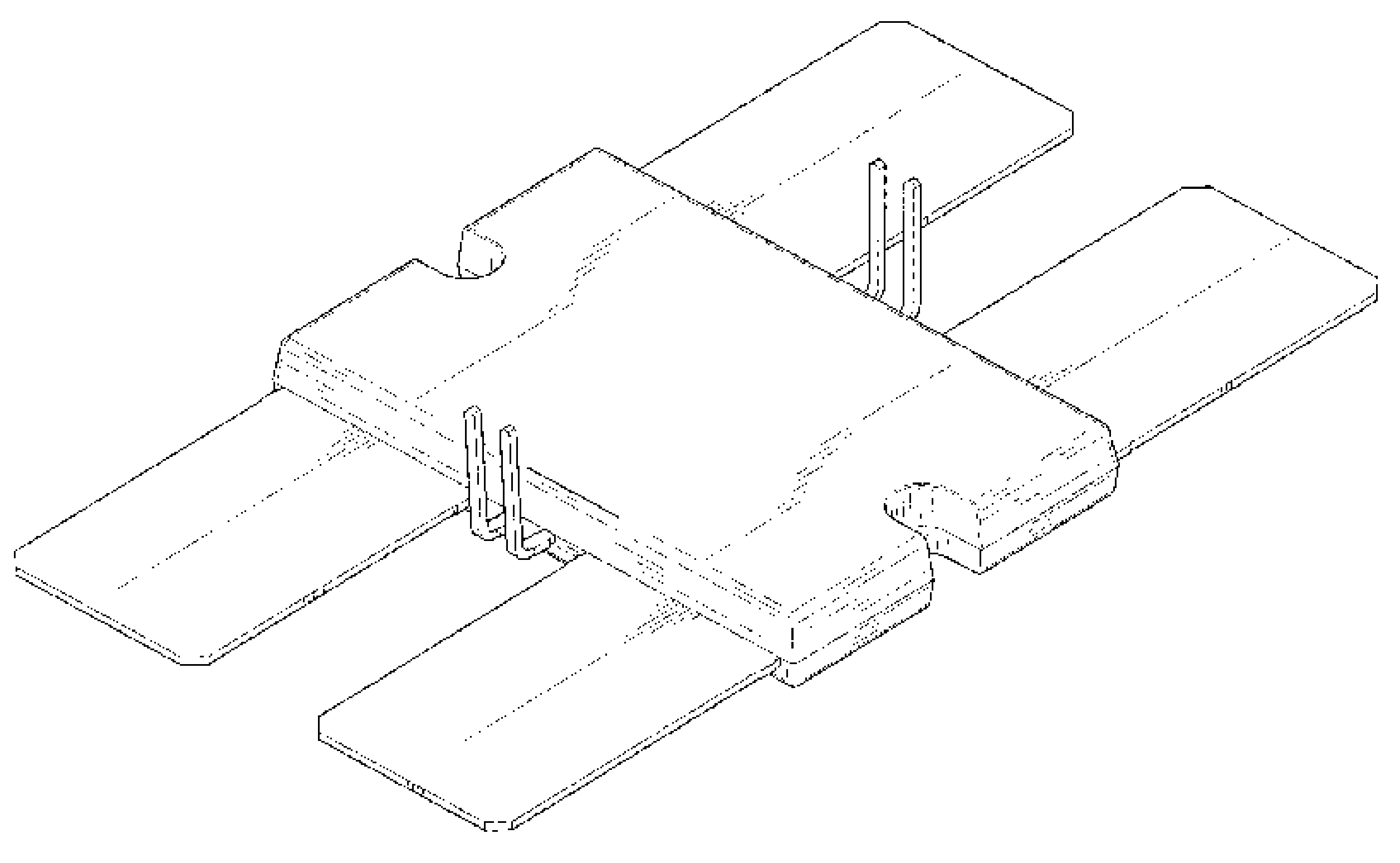
(57) **CLAIM**

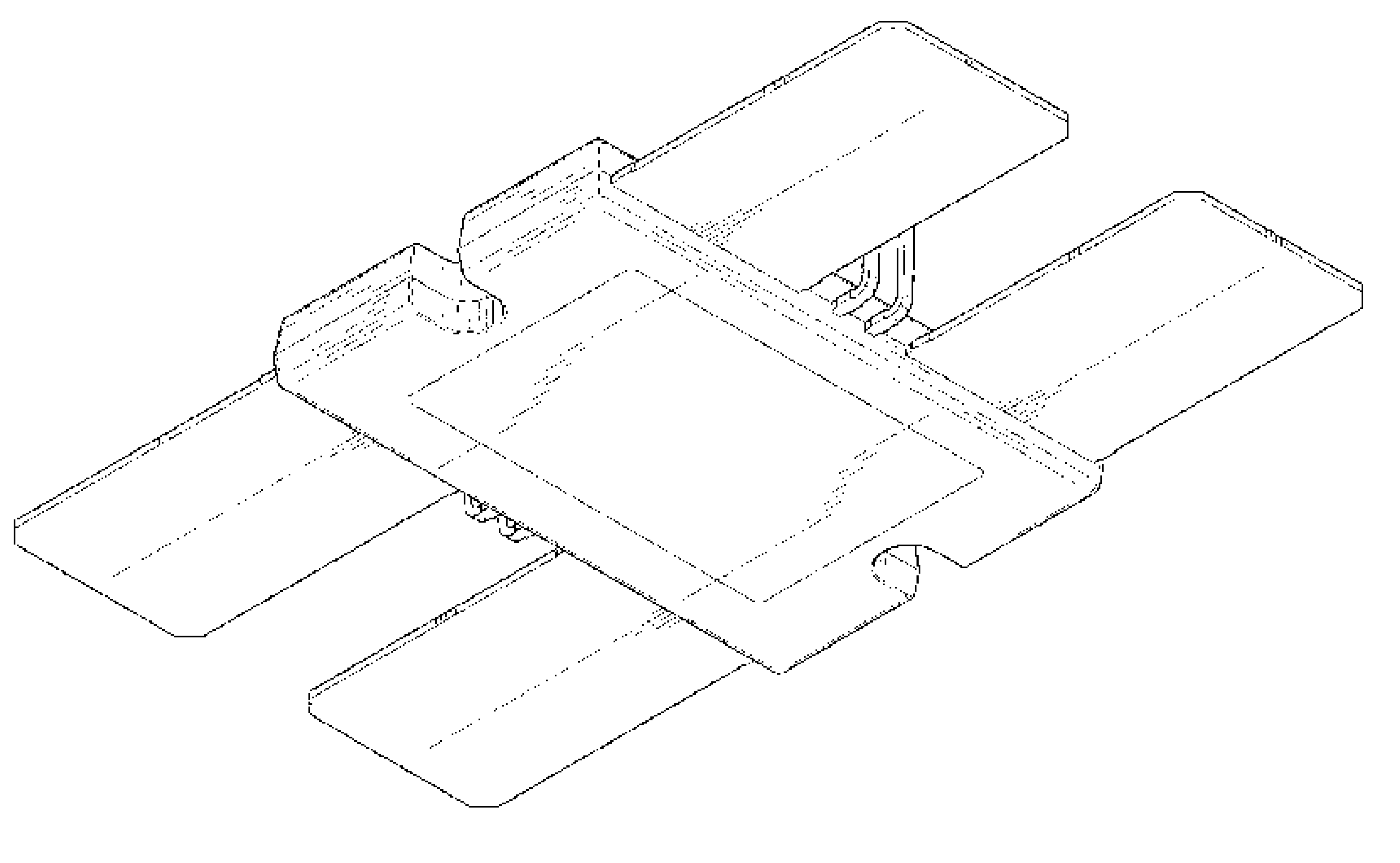
The ornamental design for a solid state relay, as shown and described.

DESCRIPTION

FIG. **1** is a front, top, left-side perspective view of the solid state relay;
FIG. **2** is a front elevational view thereof, the rear elevational view (not provided) being a mirror image thereof;
FIG. **3** is a top plan view thereof;
FIG. **4** is a right-side elevational view thereof, the left-side elevational view (not provided) being a mirror image thereof;
FIG. **5** is a bottom plan view thereof; and,
FIG. **6** is a rear, bottom, left-side perspective view thereof.
The broken lines in the drawings illustrate portions of the solid state relay that form no part of the claimed design.

1 Claim, 6 Drawing Sheets





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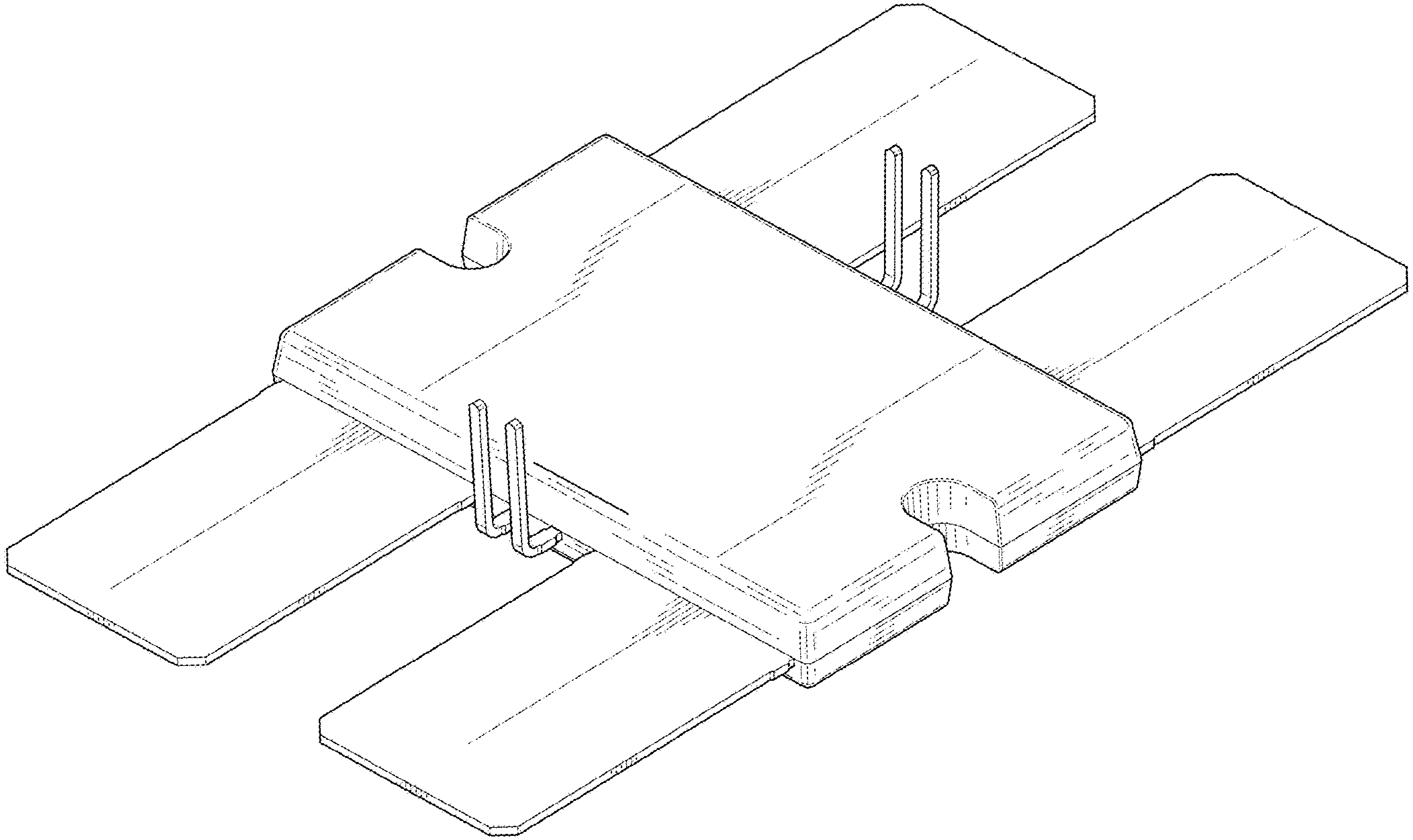

FIG. 1

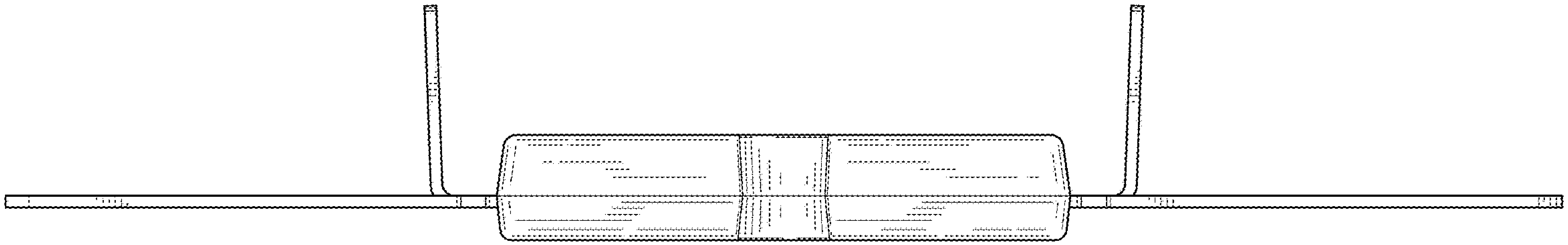

FIG. 2

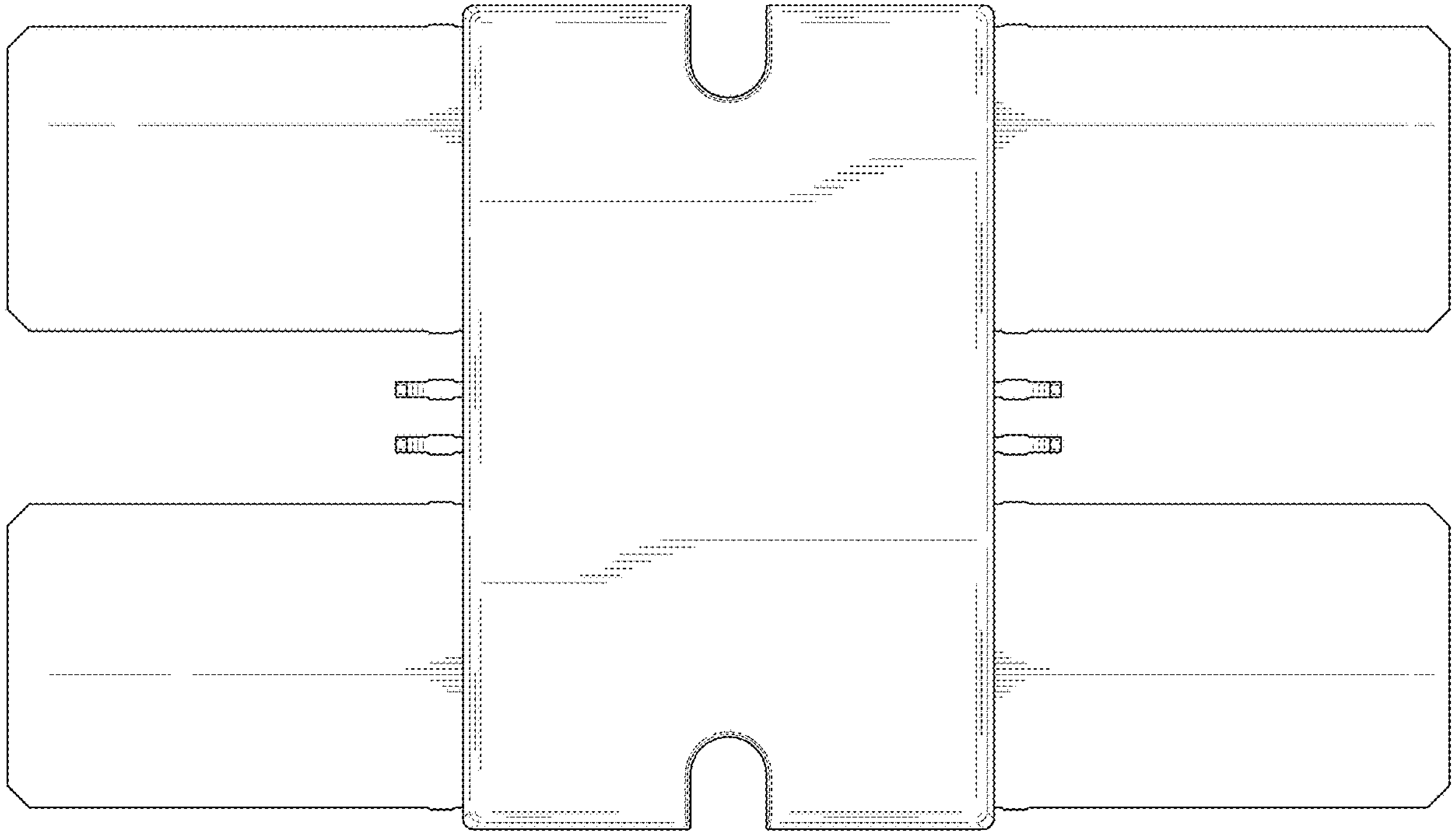

FIG. 3

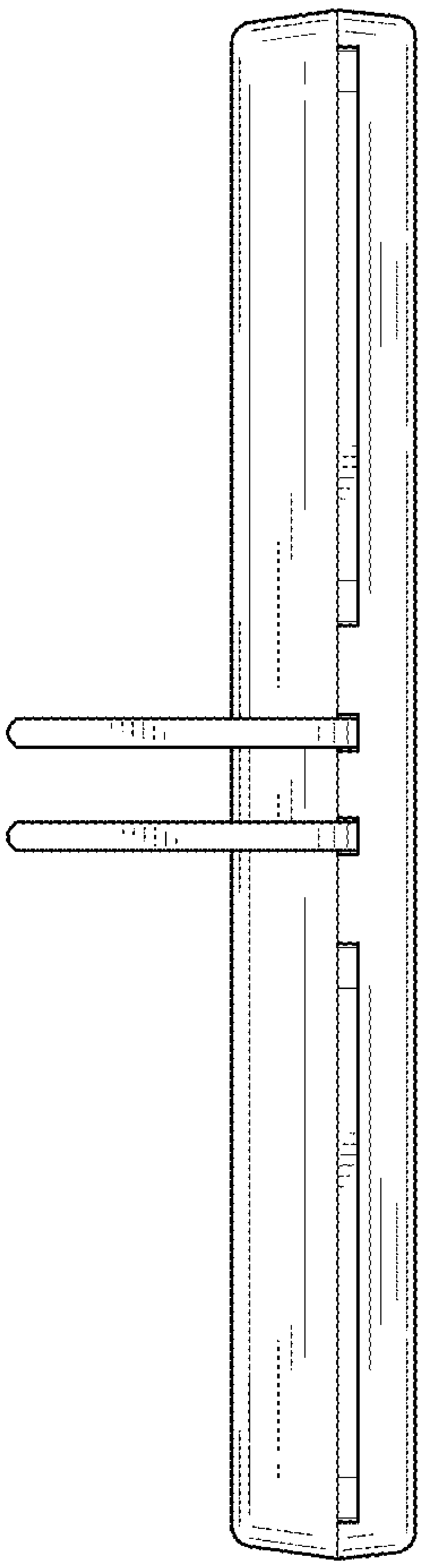

FIG. 4

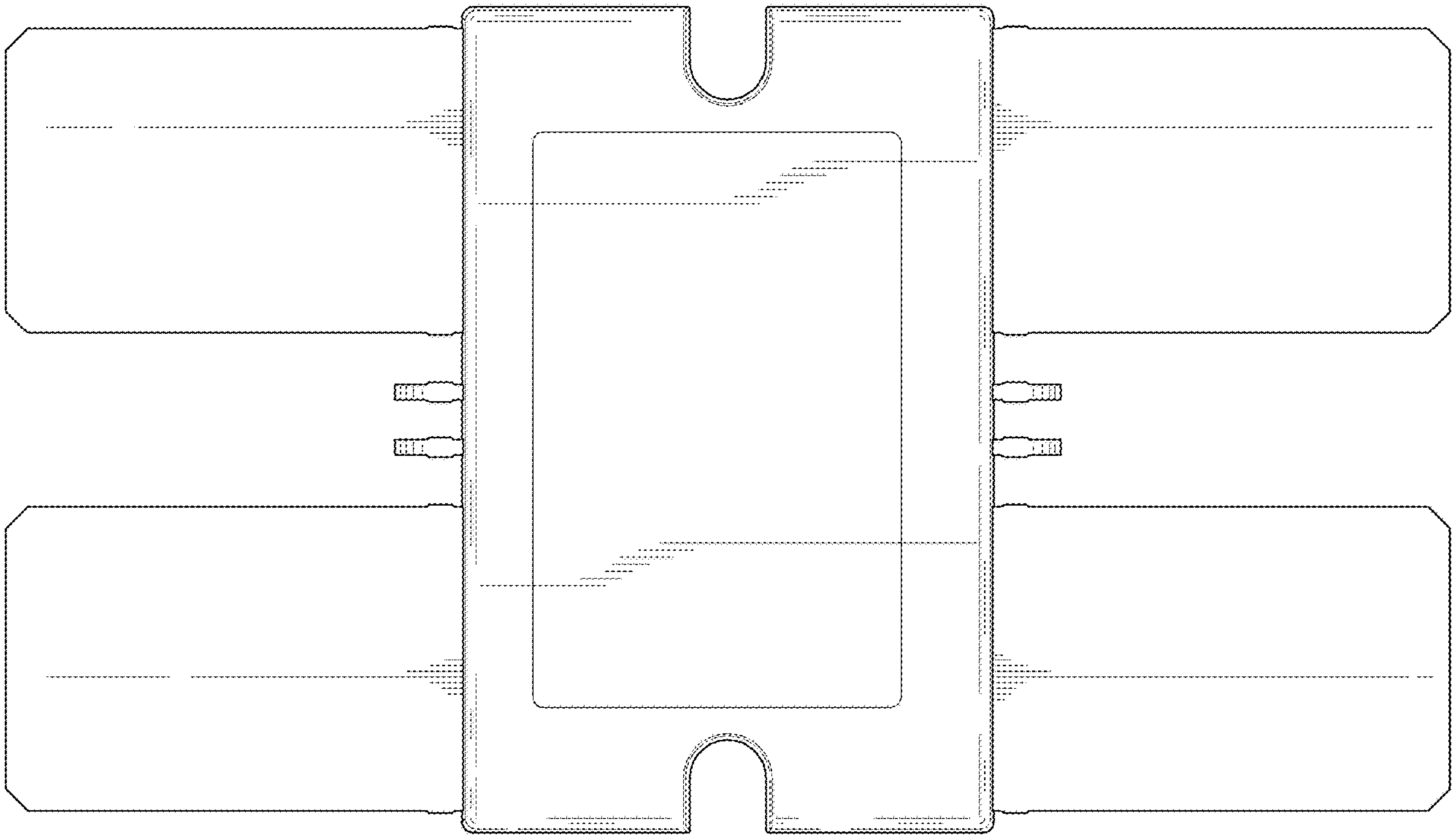

FIG. 5

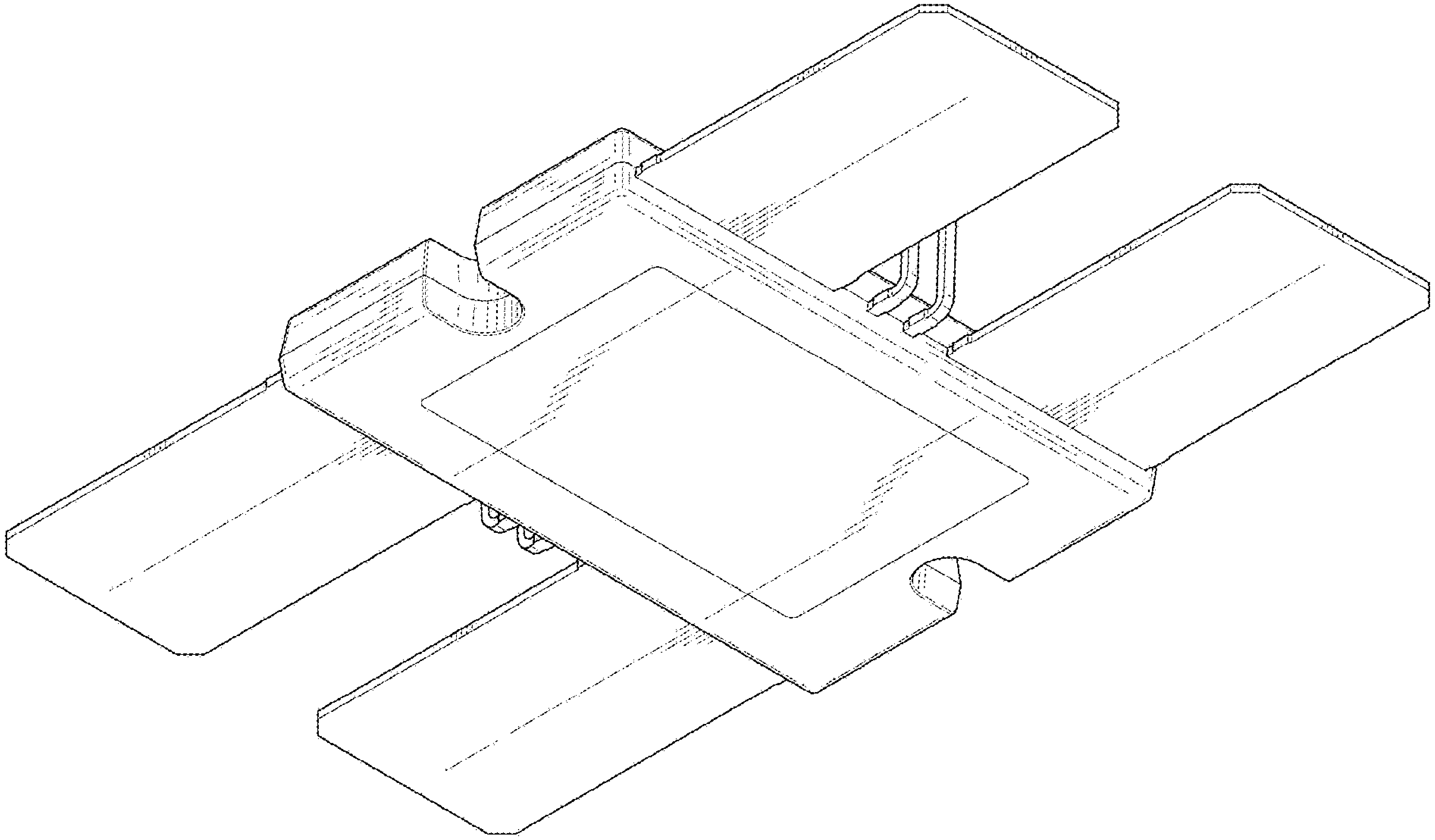

FIG. 6